



T7-2S Module Datasheet

Version: 20260413

Online Version

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The T7-2S module is a Wi-Fi and Bluetooth Low Energy (LE) combo dual-band Wi-Fi 6 module developed by Tuya Smart. It consists of a highly integrated RF chip, T7, and a few peripheral components, with built-in Wi-Fi and Bluetooth network protocol stacks and various library functions.

1. Overview

The module is built around a low-power Armv8-MC1 MCU with 512 KB SRAM, built-in 4 MB flash memory, and various peripheral resources.

T7-2S is a real-time operating system (RTOS), integrated with all Wi-Fi MAC and TCP/IP libraries. All these resources can help you develop your own embedded Wi-Fi products.

1.1. Features

- Built-in low-power Armv8-MC1 CPU that also acts as an application processor.
- Clock rate of up to 240 MHz.
- Operating voltage: 3.3V.
- Peripherals: 5 PWM pins, 1 UART (user), and 1 ADC pin.
- Wi-Fi connectivity
- IEEE 802.11a/b/g/n/ac/ax 1x1, 2.4 GHz and 5 GHz.
- Support security protocols, including WPA2, WPA2 PSK (AES), and WPA3.
- The maximum output power is +18 dBm for IEEE 802.11b and +16 dBm for 802.11a transmission.
- Support STA, AP, and STA + AP combo working modes. Except for UNII-2A/2C.
- Two pairing modes are supported, namely Bluetooth and AP mode. Both modes are suitable for pairing with Android and iOS mobile phones.
- Onboard PCB antenna with a gain of 1.91 dBi at 2.4 GHz, and 1.53 dBi at 5 GHz.
- Operating temperature range: -40°C to $+85^{\circ}\text{C}$.
- Bluetooth connectivity
- Support Bluetooth 6.0.
- Up to +6.5 dBm output power.
- Onboard PCB antenna with a gain of 1.91 dBi at 2.4 GHz, and sharing the same antenna with Wi-Fi.
- Operating temperature range: -40°C to $+85^{\circ}\text{C}$.

1.2. Scope of applications

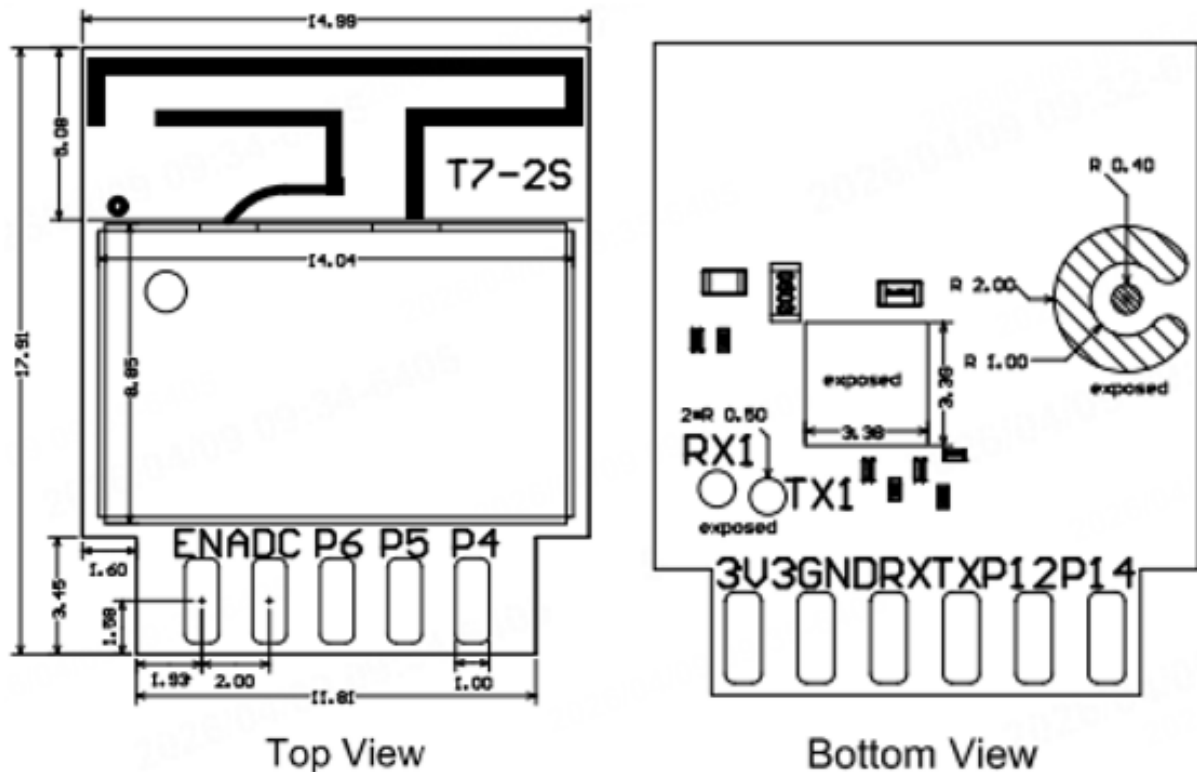
- Smart building
- Smart home and electrical appliance
- Smart socket and light
- Industrial wireless control
- Baby monitor
- IP camera
- Smart bus

2. Module interfaces

2.1. Dimensions and footprint

The T7-2S dimensions are 14.99 ± 0.35 mm (W) $\times$ 17.91 ± 0.35 mm (L) $\times$ 2.8 ± 0.15 mm (H).

The figure below shows the dimensions of the T7-2S module.



2.2. Pinout

Pin	Symbol	I/O type	Feature
1	3V3	P	Power supply pin (3.3 V).
2	P4	I/O	GPIO_4, which supports hardware PWM, corresponding to Pin 19 on the IC.
3	GND	P	Ground pin.

Pin	Symbol	I/O type	Feature
4	P5	I/O	GPIO_5, which supports hardware PWM, corresponding to Pin 18 on the IC.
5	RX0	I/O	GPIO_10, which can be reused as the UART0_RXD pin for serial communication and firmware flashing, corresponding to Pin 24 on the IC.
6	P6	I/O	GPIO_6, which supports hardware PWM, corresponding to Pin 17 on the IC.
7	TX0	I/O	GPIO_11, which can be reused as the UART0_TXD pin for serial communication and firmware flashing, corresponding to Pin 25 on the IC.

Pin	Symbol	I/O type	Feature
8	ADC	I/O	GPIO_7, with ADC feature and 0 to 3.3V input voltage range, corresponding to Pin 16 on the IC.
9	P12	I/O	GPIO_12, which supports hardware PWM, corresponding to Pin 26 on the IC.
10	CEN	I/O	The enable pin that is active low. The module has pulled up the high level, and users can control this pin externally.
11	P14	I/O	GPIO_14, which supports hardware PWM, corresponding to Pin 36 on the IC.

Pin	Symbol	I/O type	Feature
TP2	TX1	I/O	GPIO_1, which can be reused as the UART1_Log_TXD pin to send logs. After pulling it low, it will enter ATE mode when powered on. It can be configured as a normal GPIO, corresponding to Pin 20 on the IC.
TP3	RX1	I/O	GPIO_0, which can be reused as the UART1_Log_RXD pin to receive logs. It can be configured as a normal GPIO, corresponding to Pin 21 on the IC.

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P indicates the power pin, and I/O indicates the input and output pin.

3. Electrical parameters

3.1. Absolute electrical parameters

Parameter	Description	Minimum value	Maximum value	Unit
Ts	Storage temperature	−40	125	°C
VBAT	Supply voltage	3	3.6	V
Electrostatic discharge voltage (human body model)	TAMB-25°C	-	2	kV
Electrostatic discharge voltage (machine model)	TAMB-25°C	-	0.5	kV

3.2. Normal operating conditions

Parameter	Description	Minimum value	Typical value	Maximum value	Unit
Ta	Operating temperature	−40	-	85	°C
VBAT	Supply voltage	3	3.3	3.6	V
VIL	I/O low-level input	−0.3	-	0.3 VIO	V
VIH	I/O high-level input	0.7 VIO	-	VIO + 0.3	V

Parameter	Description	Minimum value	Typical value	Maximum value	Unit
VOL	I/O low-level output	-	-	0.1 V _{IO}	V
VOH	I/O high-level output	0.8 V _{IO}	-	-	V
I _{max}	I/O drive current	-	-	12	mA

3.3. Power consumption during continuous transmission and reception

2.4 GHz transmission and reception

Work state	Mode	Rate	Transmit/Receive power	Typical value	Unit
Transmit	802.11b	11 Mbit/s	+18 dBm	328	mA
Transmit	802.11g	6 Mbit/s	+17 dBm	310	mA
Transmit	802.11n-HT20	MCS0	+16 dBm	294	mA
Transmit	802.11n-HT40	MCS0	+13 dBm	246	mA
Transmit	802.11ax-HE20	MCS0	+13 dBm	248	mA
Receive	802.11b	11 Mbit/s	Continuous reception	45	mA
Receive	802.11g	6 Mbit/s	Continuous reception	45	mA
Receive	802.11n-HT20	MCS0	Continuous reception	45	mA
Receive	802.11n-HT40	MCS0	Continuous reception	45	mA

Work state	Mode	Rate	Transmit/ Receive power	Typical value	Unit
Receive	802.11ax- HE20	MCS0	Continuous reception	45	mA

5 GHz transmission and reception

Work state	Mode	Rate	Transmit/ Receive power	Typical value	Unit
Transmit	802.11a	6 Mbit/s	+16 dBm	320	mA
Transmit	802.11n- HT20	MCS0	+15 dBm	300	mA
Transmit	802.11n- HT40	MCS0	+13 dBm	280	mA
Transmit	802.11ac- VHT20	MCS0	+13 dBm	280	mA
Transmit	802.11ax- HE20	MCS0	+13 dBm	280	mA
Receive	802.11a	6 Mbit/s	Continuous reception	48	mA
Receive	802.11n- HT20	MCS0	Continuous reception	48	mA
Receive	802.11n- HT40	MCS0	Continuous reception	48	mA
Receive	802.11ac- VHT20	MCS0	Continuous reception	48	mA
Receive	802.11ax- HE20	MCS0	Continuous reception	48	mA

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The above data is based on the module being powered by a DC regulated power supply at 3.3V and operating in continuous transmission mode with a 100% duty cycle. The test data varies slightly between different modules.

3.4. Operating current

Operating mode	Status (Ta = 25°C)	Average value	Max (Typical) value	Unit
Pairing over AP	The module is in AP mode. The Wi-Fi network status indicator blinks slowly.	48	486	mA
Pairing over Bluetooth	The module is pairing over Bluetooth. The network status indicator blinks quickly.	48	480	mA
Idle mode	The module is connected to the cloud and idle. The network status indicator is steady on.	45	468	mA

Working mode	The module is connected to the cloud and working. The network status indicator is steady on.	45	472	mA
Weakly connected mode	The module is operating in a weak wireless signal network. The network status indicator is steady off.	48	476	mA
Disconnected mode	The module is disconnected from the cloud. The network status indicator is steady off.	48	460	mA

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The above data is based on the module being powered by a DC regulated power supply at 3.3V, utilizing the Tuya general firmware v1.0.1. The test data varies slightly between different modules using the same firmware.

4. RF parameters

4.1. Basic RF features

Parameter	Description
Operating frequency	2.412 to 2.484 GHz (Ch1-11 for US/CA and Ch1-13 for EU/CN), 5.180 to 5.825 GHz
Wi-Fi standard	IEEE 802.11a/b/g/n/ac/ax (Ch1-11 for US/CA, Ch1-13 for EU/CN)
Bluetooth standard	Bluetooth LE 6.0
Data transmission rate	• IEEE 802.11b: 1, 2, 5.5, and 11 Mbit/s • IEEE 802.11a/g: 6, 9, 12, 18, 24, 36, 48, and 54 Mbit/s • IEEE 802.11n: HT20 MCS0-7 and HT40 MCS0-7 • IEEE 802.11ac: VHT20 MCS0-7 • IEEE 802.11ax: HE20 MCS0-7 • Bluetooth 6.0: 1 Mbit/s and 2 Mbit/s
Antenna type	Onboard PCB antenna with a gain of 1.91 dBi at 2.4 GHz, and 1.53 dBi at 5 GHz

4.2. Transmitter (TX) performance

2.4 GHz continuous transmission performance

Parameter	Minimum value	Typical value	Maximum value	Unit
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Parameter	Minimum value	Typical value	Maximum value	Unit
RF average output power, 802.11b CCK mode, 1 Mbit/s	-	18	-	dBm
RF average output power, 802.11b CCK mode, 11 Mbit/s	-	18	-	dBm
RF average output power, 802.11g OFDM mode, 6 Mbit/s	-	17	-	dBm
RF average output power, 802.11g OFDM mode, 54 Mbit/s	-	16	-	dBm
RF average output power, 802.11n HT20 mode, MCS0	-	16	-	dBm
RF average output power, 802.11n HT20 mode, MCS7	-	15	-	dBm

Parameter	Minimum value	Typical value	Maximum value	Unit
RF average output power, 802.11n HT40 mode, MCS0	-	13	-	dBm
RF average output power, 802.11n HT40 mode, MCS7	-	12	-	dBm
RF average output power, 802.11ax HE20 mode, MCS0	-	13	-	dBm
RF average output power, 802.11ax HE20 mode, MCS7	-	12	-	dBm
RF average output power, Bluetooth LE 6.0, 1 Mbit/s and 2 Mbit/s	-	6.5	-	dBm
Frequency error	-10	-	10	ppm

5 GHz continuous transmission performance

Parameter	Minimum value	Typical value	Maximum value	Unit
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Parameter	Minimum value	Typical value	Maximum value	Unit
RF average output power, 5G-802.11a mode, 6 Mbit/s	-	16	-	dBm
RF average output power, 5G-802.11a mode, 54 Mbit/s	-	15	-	dBm
RF average output power, 5G-802.11n HT20 mode, MCS0	-	15	-	dBm
RF average output power, 5G-802.11n HT20 mode, MCS7	-	14	-	dBm
RF average output power, 5G-802.11n HT40 mode, MCS0	-	13	-	dBm
RF average output power, 5G-802.11n HT40 mode, MCS7	-	12	-	dBm

Parameter	Minimum value	Typical value	Maximum value	Unit
RF average output power, 5G-802.11ac VHT20 mode, MCS0	-	13	-	dBm
RF average output power, 5G-802.11ac VHT20 mode, MCS7	-	12	-	dBm
RF average output power, 5G-802.11ax HE20 mode, MCS0	-	13	-	dBm
RF average output power, 5G-802.11ax HE20 mode, MCS7	-	12	-	dBm
Frequency error	-10	-	10	ppm

4.3. Receiver (RX) performance

RX sensitivity

Parameter	Minimum value	Typical value	Maximum value	Unit
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Parameter	Minimum value	Typical value	Maximum value	Unit
PER < 8%, RX sensitivity, 802.11b CCK mode, 11 Mbit/s	-	-90	-	dBm
PER < 10%, RX sensitivity, 802.11g OFDM mode, 54 Mbit/s	-	-78	-	dBm
PER < 10%, RX sensitivity, 802.11n mode, HT20-MCS7	-	-75	-	dBm
PER < 10%, RX sensitivity, 802.11n mode, HT40-MCS7	-	-72	-	dBm
PER < 10%, RX sensitivity, 802.11ax mode, HE20-MCS7	-	-72	-	dBm
PER < 10%, RX sensitivity, 5G-802.11a OFDM mode, 54 Mbit/s	-	-76	-	dBm

Parameter	Minimum value	Typical value	Maximum value	Unit
PER < 10%, RX sensitivity, 5G-802.11n mode, HT20- MCS7	-	-72	-	dBm
PER < 10%, RX sensitivity, 5G-802.11n mode, HT40- MCS7	-	-68	-	dBm
PER < 10%, RX sensitivity, 5G-802.11ac mode, VHT20- MCS7	-	-70	-	dBm
PER < 10%, RX sensitivity, 5G-802.11ax mode, HE20- MCS7	-	-70	-	dBm
PER < 30.8%, RX sensitivity, Bluetooth 6.0, 1 Mbit/s	-	-98	-	dBm

5. Antenna information

5.1. Antenna type

Only PCB antenna applies.

5.2. Antenna interference reduction

When a PCB antenna is used on a Wi-Fi module, we recommend that the module antenna is at least 15 mm away from other metal components. This can optimize the Wi-Fi performance.

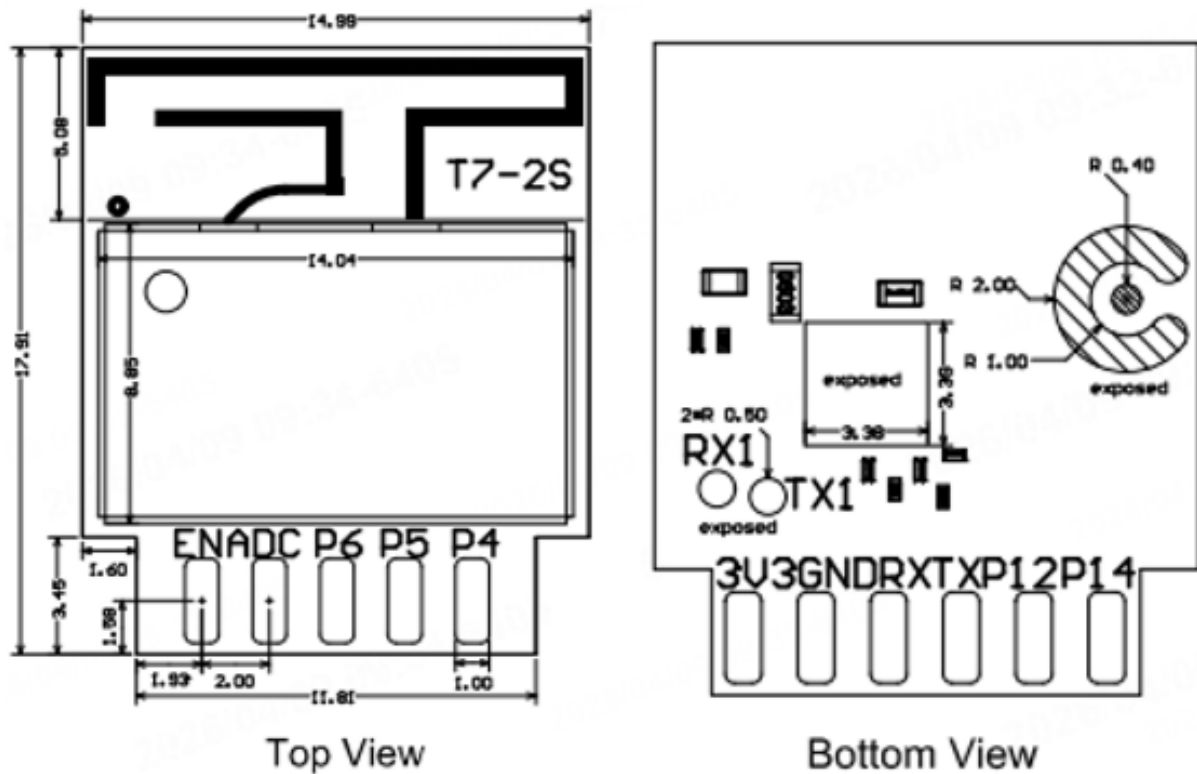
Make sure that the enclosure surrounding the antenna is not traced or filled with copper. Otherwise, the RF performance might be degraded.

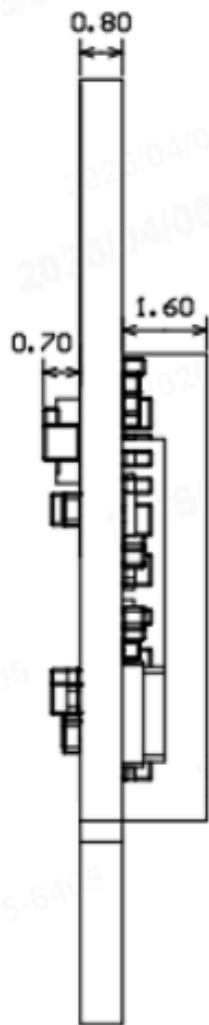
6. Packing and production instructions

6.1. Mechanical dimensions

Mechanical dimensions of the T7-2S PCB are 14.99 ± 0.35 mm (W) $\times$ 17.91 ± 0.35 mm (L) $\times$ 2.8 ± 0.15 mm (H).

The figure below shows the mechanical dimensions of T7-2S.





Unit: mm

Module form factor tolerance: $\pm 0.35\text{mm}$

PCB thickness tolerance: $\pm 0.1\text{mm}$

Shield cover height tolerance: $\pm 0.05\text{mm}$

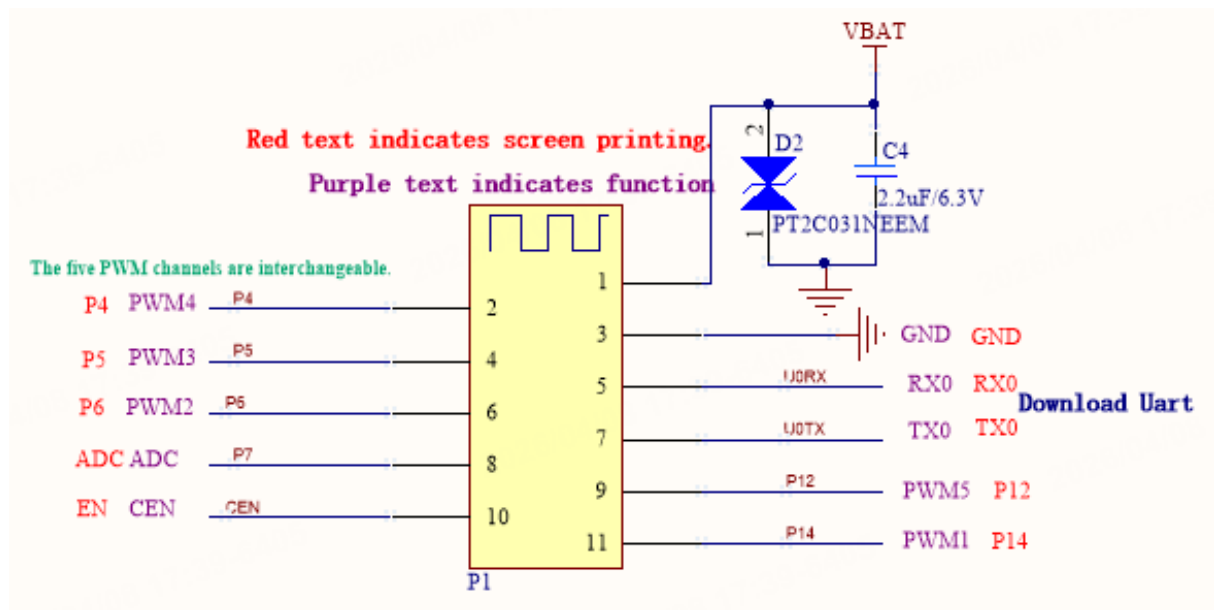
Side View

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The default tolerance of the dimensions is $\pm 0.35\text{ mm}$. If you have special requirements for key dimensions, specify them in the datasheet after consultations.

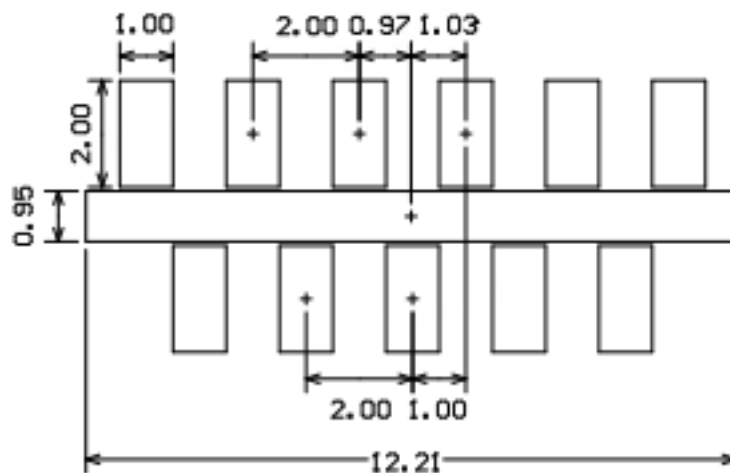
6.2. Recommended PCB footprint

Pin configuration of the T7-2S module:



PCB footprint of the T7-2S module:

Recommended footprint



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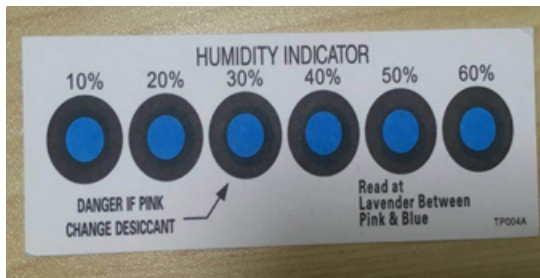
The area indicated as **keep-out** in the diagram above does not require tinning and should not have any traces routed through it.

6.3. Production instructions

- For the modules that can be packaged with the surface-mount technology (SMT) or in in-line form, you can select either of them according to the PCB

design solutions of customers. If a PCB is designed to be SMT-packaged, package the module with the SMT. If a PCB is designed to use an in-line package, use wave soldering. Complete soldering within 24 hours after the module is unpacked. Otherwise, we recommend that you place the module in a drying cupboard with a relative humidity level below 10%, or pack the module in vacuum again. Then, record the packing time and duration of exposure. The total exposure time cannot exceed 168 hours.

- Instruments or devices required for the SMT process:
 - Surface mount system
 - Solder paste inspection (SPI)
 - Reflow soldering machine
 - Thermal profiler
 - Automated optical inspection (AOI) device
- Instruments or devices required for the wave soldering process:
 - Wave soldering device
 - Wave soldering fixture
 - Constant-temperature soldering iron
 - Tin bar, tin wire, and flux
 - Thermal profiler
- Instruments or devices required for the baking process:
 - Cabinet oven
 - Electrostatic discharge (ESD) protection and heat-resistant trays
 - ESD protection and heat-resistant gloves
- A delivered module must meet the following storage requirements:
 - The moisture-proof bag must be placed in an environment where the temperature is below 40°C and the relative humidity is lower than 90%.
 - The shelf life of a dry-packaged product is 12 months from the date when the product is packaged and sealed.
 - A humidity indication card (HIC) is put in the sealed package.



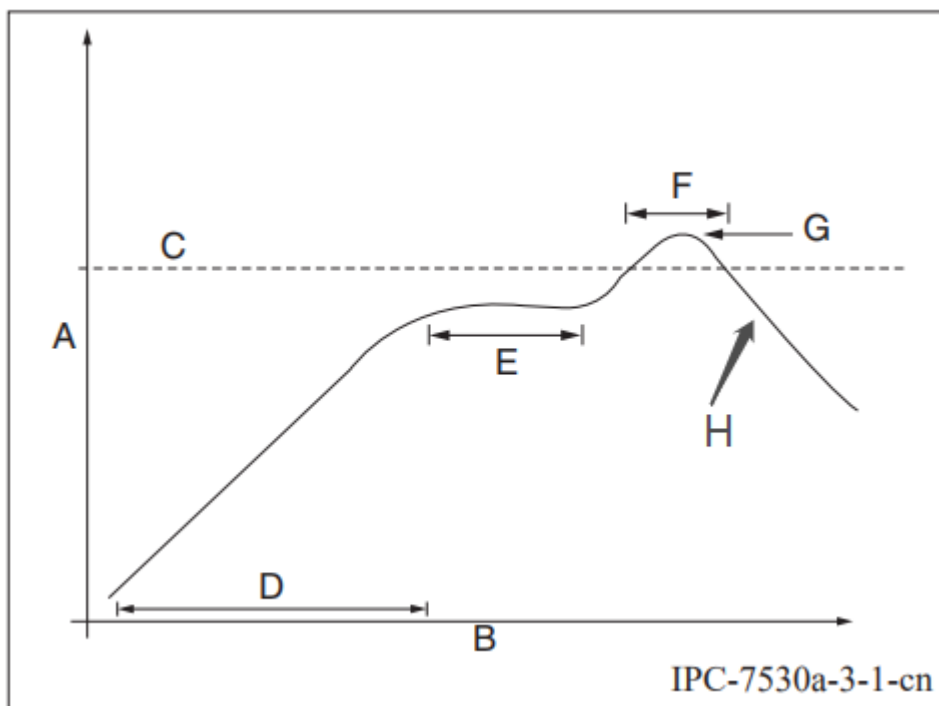
- The module needs to be baked in the following cases:
- The vacuum packaging bag is damaged before unpacking.
- After unpacking, no HIC is found in the packaging bag.
- After unpacking, the HIC indicates a humidity level of 10% or higher. In this case, the circle turns pink on the HIC.
- The total exposure time has lasted for over 168 hours since unpacking.
- More than 12 months have passed since the first sealing of the bag.
- The baking parameter settings are described below:
- Baking temperature: 40°C for reel packaging with relative humidity $\leq 5\%$. And 125°C for tray packaging with relative humidity $\leq 5\%$ (use a heat-resistant tray, rather than a plastic container).
- Baking time: 168 hours for reel packaging and 12 hours for tray packaging.
- Temperature for triggering an alert: 50°C for reel packaging and 135°C for tray packaging.
- Production can begin after a module has cooled down to below 36°C under natural conditions.
- If a module remains unused for over 168 hours after being baked, it needs to be baked again.
- If a batch of modules is not baked after exposure for more than 168 hours, do not use wave soldering to solder them. Because these modules are level-3 moisture-sensitive devices, they are very likely to get damp when exposed beyond the allowable time. In this case, if they are soldered at high temperatures, device failure or poor soldering performance might occur.
- In the whole production process, take electrostatic discharge (ESD) protective measures.
- To guarantee the pass rate, we recommend that you use the SPI and AOI to monitor the quality of solder paste printing and mounting.

6.4. Recommended oven temperature curve

Select a proper soldering technique according to the process. For more information, refer to the recommended oven temperature curve of either reflow soldering or wave soldering. The set temperatures might deviate from the actual temperature measurements. All temperatures shown in this module datasheet are obtained through actual measurements.

Technique 1: SMT process (recommended oven temperature curve of reflow soldering)

Set the oven temperatures according to the following curve.



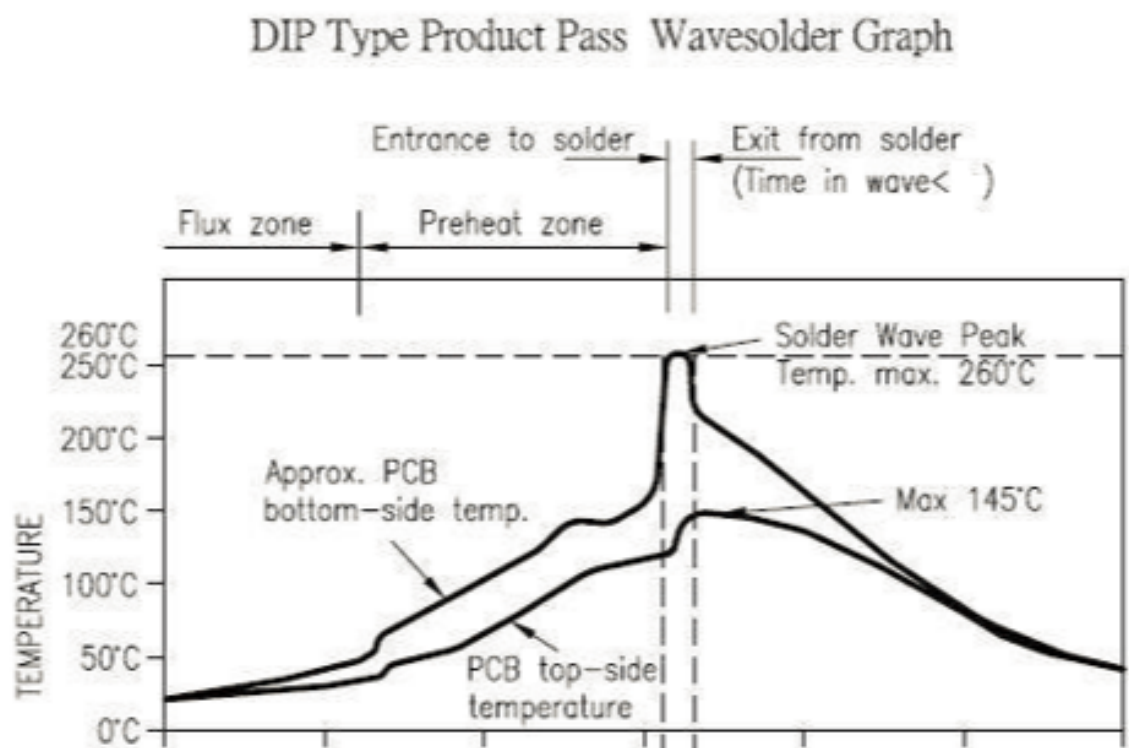
- A: temperature axis
- B: time axis
- C: alloy liquidus temperature from 217°C to 220°C
- D: ramp-up slope from 1°C/s to 3°C/s
- E: keep a constant temperature from 150°C to 200°C for a time period of 60s to 120s
- F: temperature above liquidus temperature for 50s to 70s
- G: peak temperature from 235°C to 245°C
- H: ramp-down slope from 1°C/s to 4°C/s

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The curve above is based on solder paste SAC305. For more information about other solder pastes, see the recommended oven temperature curve in the specified solder paste specifications.

Technique 2: Wave soldering process (oven temperature curve of wave soldering)

Set the oven temperatures according to the following temperature curve of wave soldering. The peak temperature is $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$.



Suggestions on wave soldering		Suggestions on manual repair soldering	
Preheat temperature	80°C to 130°C	Soldering temperature	360°C ± 20°C
Preheat duration	75s to 100s	Soldering duration	Less than 3s/point
Contact duration at the peak	3s to 5s	N/A	N/A
Solder tank temperature	260°C ± 5°C	N/A	N/A

Suggestions on wave soldering		Suggestions on manual repair soldering	
Ramp-up slope	$\leq 2^{\circ}\text{C/s}$	N/A	N/A
Ramp-down slope	$\leq 6^{\circ}\text{C/s}$	N/A	N/A

6.5. Storage conditions

	Caution This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL 3
		If blank, see adjacent bar code label
1. Calculated shelf life in sealed bag: 12 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH)		
2. Peak package body temperature: <u>260</u> $^{\circ}\text{C}$ If blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>168</u> hours of factory conditions If blank, see adjacent bar code label $\leq 30^{\circ}\text{C}/60\% \text{ RH}$, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads $>10\%$ for level 2a - 5a devices or $>60\%$ for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <u>See Production Date</u> If blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

7. MOQ and packaging information

Product model	MOQ (pcs)	Shipping packaging	Modules per reel	Reels per carton
T7-2S	4,400	Tape and reel	1,100	4

8. Appendix: Statement

Important Notice to OEM integrators

1. This module is limited to OEM installation ONLY.
2. This module is limited to installation in mobile or fixed applications, according to Part 2.1091(b).
3. The separate approval is required for all other operating configurations, including portable configurations with respect to Part 2.1093 and different antenna configurations.
4. For FCC Part 15.31 (h) and (k): The host manufacturer is responsible for additional testing to verify compliance as a composite system. When testing the host device for compliance with Part15 Subpart B, the host manufacturer is required to show compliance with Part 15 Subpart B while the transmitter module(s) are installed and operating. The modules should be transmitting and the evaluation should confirm that the module's intentional emissions are compliant (i.e. fundamental and out of band emissions). The host manufacturer must verify that there are no additional unintentional emissions other than what is permitted in Part 15 Subpart B or emissions are compliant with the transmitter(s) rule(s).The Grantee will provide guidance to the host manufacturer for Part 15 B requirements if needed.

Important Note

Notice that any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify Tuya that they wish to change the antenna trace design. In this case, a Class II permissive change application is required to be filed by the TUYA, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive change application.

End Product Labeling When the module is installed in the host device, the FCC label must be visible through a window on the final device or it must be visible when an access panel, door, or cover is easily removed. If not, a second label must be placed on the outside of the final device that contains the following text: "Contains FCC ID: 2ANDL-T72S".The FCC ID can be used only when all FCC compliance requirements are met.

Antenna Installation (1) The antenna must be installed such that 20 cm is maintained between the antenna and users, (2) The transmitter module may not be co-located with any other transmitter or antenna. (3) Only antennas of the same type and with equal or less gains as shown below may be used with this module. Other types of antennas and/or higher gain antennas may require additional authorization for operation.

Antenna type	BT/Wlan 2.4G	UNII-1	UNII-2	UNII-2C	UNII-3
PCB	1.91dBi	-1.64dBi	-0.55dBi	0.8dBi	1.53dBi

In the event that these conditions cannot be met (for example, certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid, and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

Manual Information to the End User The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warnings as shown in this manual.

Federal Communication Commission Interference Statement This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or

television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

List of applicable FCC rules This module has been tested and found to comply with Part 15 requirements for Modular Approval. The modular transmitter is only FCC authorized for the specific rule parts (i.e., FCC transmitter rules) listed on the grant, and that the host product manufacturer is responsible for compliance with any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product as being Part 15 Subpart B compliant (when it also contains unintentional-radiator digital circuitry), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.

This device is intended only for OEM integrators under the following conditions:
(For module device use)

1. The antenna must be installed such that 20 cm is maintained between the antenna and users, and
2. The transmitter module may not be co-located with any other transmitter or antenna.

As long as 2 conditions above are met, further transmitter tests will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Radiation Exposure Statement This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with a minimum distance of 20 cm between the radiator & your body.